Effect of \( \text{O}_2/\text{Ar} \) flow ratio and post-deposition annealing on the structural, optical and electrical characteristics of \( \text{SrTiO}_3 \) thin films deposited by RF sputtering at room temperature

E. Goldenberg\textsuperscript{a,⁎}, T. Bayrak\textsuperscript{a,b}, C. Ozgit-Akgun\textsuperscript{a,b}, A. Haider\textsuperscript{a,b}, S. A. Leghari\textsuperscript{a,b}, M. Kumar\textsuperscript{a}, N. Biyikli\textsuperscript{a,b}

\textsuperscript{a} National Nanotechnology Research Center (UNAM), Bilkent University, Ankara 06800, Turkey
\textsuperscript{b} Institute of Materials Science and Nanotechnology, Bilkent University, Ankara 06800, Turkey

A R T I C L E   I N F O

Article history:
Received 3 April 2015
Received in revised form 8 July 2015
Accepted 26 July 2015
Available online 29 July 2015

Keywords:
Thin film
Strontium titanate (\( \text{SrTiO}_3 \))
RF magnetron sputtering
Optical properties
Electrical properties
Dielectric constant

A B S T R A C T

\( \text{SrTiO}_3 \) (STO) thin films have been prepared by reactive RF magnetron sputtering on Si (100) and UV fused silica substrates at room temperature. The effect of oxygen flow on film characteristics was investigated at a total gas flow of 30 sccm, for various \( \text{O}_2/\text{O}_2 + \text{Ar} \) flow rate ratios. As-deposited films were annealed at 700 °C in oxygen atmosphere for 1 h. Post-deposition annealing improved both film crystallinity and spectral transmittance. Film microstructure, along with optical and electrical properties, was evaluated for both as-deposited and annealed films. Abroad photoluminescence emission was observed within the spectral range of 2.75–3.50 eV for all STO thin films irrespective of their deposition parameters. Upon annealing, the optical band gap of the film deposited with 0% \( \text{O}_2 \) concentration slightly blue-shifted, while the other samples grown at higher oxygen partial pressure did not show any shift. Refractive indices (\( n \)) (at 550 nm) were in the range of 2.05 to 2.09, and 2.10 to 2.12 for as-deposited and annealed films, respectively. Dielectric constant values (at 100 kHz) within the range of 30–66 were obtained for film thicknesses less than 300 nm, which decreased to ~30–38 after post-deposition annealing.

© 2015 Published by Elsevier B.V.

1. Introduction

Recently, ferroelectric oxides have gained considerable interest in microelectronic applications including integrated devices [1], ultrathin high-\( k \) gate dielectric applications [2], capacitors [3], light emitters [4], dynamic random access memories [5–7], microwave tunable devices [8], and electroluminescence elements [9–12] due to their high dielectric constants, low leakage currents, and decent optical properties. Among various \( \text{ABO}_3 \) class ferroelectric oxides, \( \text{SrTiO}_3 \) (STO) thin films, owing to their chemical stability, compatibility with high temperature processes, and attractive opto-electronic properties, have a great promise for micro-/nano-electronic applications. Single crystal, crystalline nanoparticle and polycrystalline thin film [13–16] structures for STO were noted in the literature. In crystalline form, STO thin films exhibit high dielectric constants of ~300, and moreover, they show paraelectric and ferroelectric characteristics even without permanent electric dipole [12,17]. Furthermore, in nanostructured thin film form they have the ability to show multifunctional properties [18]. STO nanostructured thin films have been deposited on a variety of substrates using various deposition techniques including electron cyclotron resonance (ECR) ion beam sputtering [19], atomic layer deposition [20], pulsed laser deposition [21,22], molecular beam epitaxy [23], metal organic chemical vapor deposition [24], and sputtering [1.25–27]. Among these methods, sputtering is simple, low cost and effective thin film growth technique which is compatible for industrial scale as well. Since the physical characteristics particularly microstructure, surface morphology, composition, and interface of STO and related materials play important role in optical and electrical characteristics, growth mechanism, as well as crystalline structure, optical and dielectric properties of these thin films have been extensively investigated over a wide deposition parameters and temperature range. It is reported that nanostructured STO thin films show different opto-electronic behavior from those of bulk crystals [28]. The variability in the oxidation state of the cation mainly accounts for the variation in physical properties of STO [29]. For example, a wide range of optical band gap values were reported between 2.70 and 4.26 eV for STO thin films as a function of fabrication techniques, their process parameters and oxidation states [30,31]. Furthermore, high dielectric constant values were mostly obtained for thick STO films (~200 nm), which were deposited at relatively high substrate temperatures [1,15,16,25,26] and on substrate materials which are not compatible with integrated circuit processes. It is also reported by Weiss et al. that STO thin films deposited on Si often have reduced dielectric properties due to the thermal stresses which have a great impact on the

http://dx.doi.org/10.1016/j.tsf.2015.07.060
0040-6090/© 2015 Published by Elsevier B.V.
dielectric behavior and arise from the large difference in thermal expansion coefficients of Si and STO [32]. Despite extensive research on STO thin films most of the studies mainly focused only on the correlation between film microstructure and optical properties including photomission mechanism and optical dielectric constants [33–38], or only on their electrical characteristics. Only a limited number of experimental work were reported on room temperature (RT)-grown <200 nm-thick STO films deposited on Si substrates. In addition, to the best of our knowledge, the correlation between growth parameters and film crystallinity, microstructure, optical, and electrical properties for RT-grown STO thin films has not yet been reported and many multifunctional properties remain unclear for these nanostructured materials.

A thorough understanding of the material requires a systematic study, therefore, it is essential to correlate the film characteristics with sputtering parameters. In the present work, STO has been deposited directly on Si (100) and UV fused silica (UVFS) substrates by RF magnetron sputtering at RT in order to investigate the effects of O2 flow and post-deposition annealing on the structural, optical, and electrical properties of the deposited thin films.

2. Experimental methodology

2.1. Film deposition

STO thin films were deposited on Si (100) and UVFS substrates by VAKSIS NanoD-4S RF magnetron sputtering system at RT. The depositions were performed using STO ceramic targets (50 mm) with a constant target-to-substrate distance of 50 mm. The base pressure in the chamber was lower than 0.9 MPa. STO films were deposited using an RF power of 75 W (13.56 Hz) at 0.40 Pa total deposition pressure. Oxygen content in the films was varied by changing the O2/Ar flow rate while the total flow was kept constant at 30 sccm. In the present work three different O2 concentrations (O2/Ar + O2); i.e., 0%, 10%, and 20%, were evaluated. For ease of discussion, films deposited using 0%, 10%, and 20% O2 are referred as STO0, STO10, and STO20, respectively. In order to investigate the effect of post-deposition annealing on structural, optical, and electrical properties, films were annealed at 700 °C for 1 h in O2 environment. Annealing was performed using ATUV-Unit hern (RTA SRO-704) rapid thermal annealing system with a constant O2 flow of 200 sccm. The heating rate was 10 °C/s, and the samples were taken out from the annealing chamber after the system was cooled down below 80 °C. The deposition conditions are summarized in Table 1.

<table>
<thead>
<tr>
<th>Deposition Parameters</th>
<th>Values</th>
</tr>
</thead>
<tbody>
<tr>
<td>Base pressure (MPa)</td>
<td>&lt;0.9</td>
</tr>
<tr>
<td>Deposition pressure (Pd) (Pa)</td>
<td>0.40</td>
</tr>
<tr>
<td>O2/Ar + O2 flow ratio</td>
<td>0%, 10%, and 20%</td>
</tr>
<tr>
<td>RF power (W)</td>
<td>75</td>
</tr>
<tr>
<td>Total gas flow (sccm)</td>
<td>30</td>
</tr>
<tr>
<td>Target size (mm)</td>
<td>50</td>
</tr>
<tr>
<td>Target-substrate holder distance (mm)</td>
<td>50</td>
</tr>
<tr>
<td>Deposition time (min)</td>
<td>15–25</td>
</tr>
</tbody>
</table>

2.2. Film characterization

Grazing-incidence X-ray diffraction (GIXRD) measurements were carried out in a PANalytical X’Pert PRO MRD diffractometer using Cu Kα (λ = 1.5406 Å) radiation with an angle of incidence (ω) of 0.3°. The GIXRD patterns were recorded within the 2 Theta range of 20°–80° with a step size and counting time of 0.1° and 10 s, respectively. The interplanar spacing (dhkl) was calculated for the most intense peak using Bragg’s law [39]. Lattice parameter was roughly calculated by substituting d011 values in Eq. (1), which relates the interplanar spacing (dhkl), miller indices (hkl), and lattice parameter (a) for cubic crystals.

\[ d = \frac{a}{\sqrt{h^2 + k^2 + l^2}} \]  

Crystallite sizes of the annealed films were estimated from the (011) reflection using the well-known Scherrer formula by neglecting the instrumental broadening and assuming that the observed broadening is only related to the size effect [39,40].

Bulk film chemical compositions and bonding states were determined by X-ray photoelectron spectroscopy (XPS) using Thermo Scientific K-Alpha spectrometer with a monochromatized Al Kα X-ray source (1486.6 eV). Ar ion beam having an acceleration voltage of 1 kV was used to etch samples for ~30 s. Peak analyses were performed using the Avantage Software. Surface morphology was investigated using scanning electron (SEM, FEI Nova NanoSEM 430) and atomic force microscopes (AFM, Asylum Research MFP-3D), latter operating in the tapping mode using a triangular tip.

Optical measurements were performed using an ultraviolet–visible–near infrared (UV–VIS–NIR) single beam spectrophotometer (Ocean Optics HR4000CG-UV-NIR) in the wavelength range of 250–1000 nm relative to air, and a variable angle spectroscopic ellipsometer (VASE, J.A. Woollam) with rotating analyzer and xenon light source. The optical properties were modeled using the homogeneous Tauc–Lorentz (TL) function for four-layer model including the substrate, SiO2 layer (~2 nm), STO film, and surface roughness to improve the fitting quality. If not stated otherwise, all n and k values in this paper correspond to the wavelength of 550 nm. Best fit data were used for the determination of optical constants and film thickness “t”. In addition, film surface roughness was determined using ellipsometry analysis; the absorption coefficient, α(λ) = 4πκ(λ)/λ, was calculated from the k(λ) values. The optical band gap energy, EC, was evaluated using the absorption coefficient, associated with direct transition photon absorption:

\[ \alpha(E) = \frac{B(E-E_g)^m}{E} \]  

where E (>Eg) is the photon energy, and m is a power factor generally being 1/2 or 2 for direct and indirect bandgap materials, respectively. Assuming that m = 1/2 or 2, direct and indirect band gap energies were defined by extrapolation of the linear part of the absorption spectrum to (αE)1/m = 0 [41]. Photoluminescence (PL) measurements were performed using a fluorescence spectrophotometer (Carry, Eclipse fluorescence spectrophotometer) as a function of deposition and post-deposition annealing parameters in the wavelength range of 320 nm to 605 nm. The excitation wavelength was chosen to be 310 nm.

Metal–insulator–semiconductor (MIS) structures with STO as the insulator layer were fabricated on p-type Si substrates in order to study the electrical properties of deposited films. Capacitance–voltage (C–V) and current–voltage (I–V) behaviors of the fabricated structures were tested using a semiconductor parameter analyzer (Keithley 4200-SCS), which was connected to a probe station (Cascade Microtech PM-5). Silver (Ag) electrical contacts were deposited using thermal evaporation. C–V characteristics of the as-deposited and annealed STO films were determined between –2 V and +2 V at different frequencies; i.e., 50, 100, 300, and 600 kHz. Dielectric constants (εr) were calculated from the measurements carried out at 100 kHz using the parallel-capacitor model [42]. In addition, charge storage capacity (CSC = εrε0Ed) of the films were calculated from the I–V measurements.
3. Results and discussion

3.1. Film morphology and structure

Film crystallinity and the formation of crystalline phases are affected by the process parameters and the post-deposition annealing temperature. All RT-grown STO samples were amorphous in their as-deposited state, as determined by GIXRD measurements. GIXRD patterns of as-deposited STO20, annealed STO0, STO10 and STO20 films are demonstrated in Fig. 1. Upon annealing at 700 °C for 1 h under O2 atmosphere, STO20 became polycrystalline, whereas films deposited at low O2 flow rates were amorphous or nano-crystalline. Nano-crystallite formation was ascribed to the observed relatively broad diffraction peaks observed between 25° and 35°, compare to as-deposited sample. For the polycrystalline film, the major phase was identified to be cubic STO (ICSD code: 98-018-1652) with (001), (011), (111), (002), (012), (112), (022), and (113) reflections appearing at 22.3°, 32.3°, 39.7°, 46.4°, 52.3°, 57.7°, 67.8°, and 77.0° 2Theta positions, respectively. On the other hand, the remaining reflection at 27.8° was related to the formation of rutile TiO2 phase (ICSD code: 98-008-5494). The interplanar spacing for 67.8°, and 77.0° 2Theta positions, respectively. Nano-crystallite formation rates were amorphous or nano-crystalline. Nano-crystallite formation inferred in Fig. 1. Upon annealing at 700 °C for 1 h under O2 atmosphere, heated substrates and/or annealed at high temperatures after its deposition show amorphous or nano-crystalline morphology (which is not shown here). 3D AFM surface scans of annealed STO films were examined by SEM and AFM. Surface morphologies of STO films were examined by SEM and AFM. As revealed by SEM images, as-deposited thin films were found to possess a smooth surface, whereas annealed films had a grainy surface morphology (which is not shown here). 3D AFM surface scans of annealed STO10 and STO20 thin films are presented in Fig. 2. Root mean square (RMS) roughnesses of the as-deposited films were determined as <0.2 nm (0.12 and 0.16 nm) independent of the deposition parameters. After post-deposition annealing, roughness values of the films increased up to 2.7 nm. Polycrystalline film exhibited a slightly higher roughness value as a result of the formation of larger grains. These results were confirmed with spectroscopic ellipsometry analysis as well.

3.2. Optical properties

Fig. 3 presents the optical transmission vs. wavelength plots of as-deposited and annealed STO thin films. It is seen that the film transmittance is approximately ~60% in the VIS and NIR spectral regions for the film deposited using 0% O2; whereas, for films deposited in O2 rich environment it reaches to ~70%. After the post-deposition annealing, average transmission values increased up to ~80% in the same spectrum. All as-deposited and annealed thin films showed well-defined absorption edges in the UV spectrum. Absorption edges of the films shifted to lower wavelengths with the introduction of O2 during sputtering. In our XRD analysis, we observed TiO2 sub-oxide phase formation, hence lower film dielectric responses. In our XRD analysis, we observed TiO2 sub-oxide phase formation which is consistent with the XPS analysis.

Surface morphologies of STO films were examined by SEM and AFM. As revealed by SEM images, as-deposited thin films were found to possess a smooth surface, whereas annealed films had a grainy surface morphology (which is not shown here). 3D AFM surface scans of annealed STO10 and STO20 thin films are presented in Fig. 2. Root mean square (RMS) roughnesses of the as-deposited films were determined as <0.2 nm (0.12 and 0.16 nm) independent of the deposition parameters. After post-deposition annealing, roughness values of the films increased up to 2.7 nm. Polycrystalline film exhibited a slightly higher roughness value as a result of the formation of larger grains. These results were confirmed with spectroscopic ellipsometry analysis as well. In films which might be due to energetic Ar ion etching. As can be seen from the table, Sr/Ti concentration ratio was 0.80, 0.44 and 0.46 for films deposited at 0%, 10% and 20% O2 concentrations, respectively. Annealing has significant effect on films deposited at oxygen rich environment. After annealing Sr/Ti concentration ratio increased for films deposited with 10% and 20% O2 concentration, while it remained almost constant for films deposited at 0% O2. This might be due to diffusion of Sr and Ti atoms with annealing. High resolution XPS analysis indicated Ti and O-rich STO films. Excess Ti and O might favor sub-oxide phase formation, hence lower film dielectric responses, in our XRD analysis, we observed TiO2 sub-oxide phase formation which is consistent with the XPS analysis.

<table>
<thead>
<tr>
<th>O2 flow ratio condition</th>
<th>Sr at.%</th>
<th>Ti at.%</th>
<th>O at.%</th>
<th>Ar at.%</th>
<th>Sr/Ti</th>
</tr>
</thead>
<tbody>
<tr>
<td>0% As-deposited</td>
<td>9.59</td>
<td>11.86</td>
<td>75.34</td>
<td>3.21</td>
<td>0.81</td>
</tr>
<tr>
<td>Annealed</td>
<td>8.81</td>
<td>11.03</td>
<td>76.58</td>
<td>3.58</td>
<td>0.80</td>
</tr>
<tr>
<td>10% As-deposited</td>
<td>10.91</td>
<td>25.03</td>
<td>61.17</td>
<td>2.89</td>
<td>0.44</td>
</tr>
<tr>
<td>Annealed</td>
<td>17.65</td>
<td>16.75</td>
<td>64.06</td>
<td>1.54</td>
<td>1.05</td>
</tr>
<tr>
<td>20% As-deposited</td>
<td>11.51</td>
<td>25.03</td>
<td>60.66</td>
<td>2.80</td>
<td>0.46</td>
</tr>
<tr>
<td>Annealed</td>
<td>17.43</td>
<td>18.78</td>
<td>61.27</td>
<td>2.52</td>
<td>0.93</td>
</tr>
</tbody>
</table>

Table 2: Bulk elemental compositions of as-deposited and annealed STO thin films as determined by XPS survey scans. Data were collected after 30 s of in situ Ar etching.
on single crystalline STO films using ellipsometry, and found that STO band gap energies range from 3.58 to 3.90 eV for direct, and from 3.00 to 3.77 eV for indirect transitions as a function of oxidation/reduction. They further concluded that the reduction in band gap energies might be due to the variation in oxidation state of the film and stoichiometric changes. In the present study, indirect band gap energies are found to be within the range of data already reported in literature; however, the larger direct band gap energies, which were observed for all STO thin films, might be attributed to strain-induced defects and/or to the presence of small nano-crystallites in the microstructure.

Summary of the measured refractive index ($n$) and extinction coefficient ($k$) data of as-deposited and annealed STO thin films is presented in Table 3. Film refractive indices ($n$) were found to be between 2.05 and 2.09 for as-deposited films, which slightly increased after post-deposition annealing, indicating film densification. The effect of post-deposition annealing treatment on $n$ values is presented in Fig. 5. No significant changes were observed in the VIS spectrum ($\lambda > 400$ nm) of as-deposited STO films sputtered using 0% and 20% O$_2$ concentrations. Upon post-deposition annealing, refractive indices increased for both thin film samples. Furthermore, the change in $n$ values, however, was more pronounced for the film deposited using a higher O$_2$ flow rate. Although we obtained some stoichiometric variations in as-deposited and annealed films, we attribute the changes in optical properties to improved film microstructure and following film densification. STO film thicknesses were also extracted from the ellipsometric data, and found to be 16.4, 3.4, and 3.5 nm/min for STO$^0$, STO$^{10}$, and STO$^{20}$ films, respectively. As can be seen, the deposition rate first decreased with increasing O$_2$ flow rate, but the change was not significant with further increase.

Fig. 3. Spectral optical transmission plots of as-deposited and annealed STO thin films deposited on UVFS substrates. Annealing was carried out at 700 °C for 1 h in O$_2$ environment.

PL spectroscopy was used to determine optical properties of deposited STO films. There are many studies reporting on the photo-carrier recombination dynamics of amorphous, un-doped and doped STO thin films [31,18,28,43,44]. However, the PL emission data for un-doped amorphous STO thin films grown at low temperatures are limited in the literature. It is known that the optical properties of STO thin films strongly depend on the doped carrier density, temperature and microstructure including its crystallite size. PL emission spectrum of as-
deposited and annealed STO films on Si substrates is given in Fig. 6. A broad emission peak in the wavelength range of 350 nm (~3.5 eV) to 450 nm (~2.75 eV) was observed for all STO films. STO thin films sputtered in the oxygen deficient environment exhibited PL emission at a lower wavelength (~360 nm for STO\(^{\text{st}}\)). With the introduction of oxygen into the sputtering chamber, PL characteristics of the deposited STO films changed and a secondary emission peak appeared as a shoulder at 385 nm for STO\(^{\text{st}}\) and STO\(^{\text{st}}\) samples. The observed 385 nm (3.22 eV) peak intensity increased with the \(O_2\) flow rate. Yamada et al. reported on PL behavior of STO bulk crystals and nanoparticles under weak continuous wave and strong pulse laser excitations. They observed 2.9 eV blue emission band for bulk STO crystals, and 2.4 and 2.9 eV emission bands for STO nanoparticles under strong pulse excitation. However, at weak excitation they observed emission from 1.7, 2.4, 2.9 and 3.3 eV bands. In their work, 1.7 and 2.4 eV emission peaks are attributed to the defect or impurity related mechanisms while 2.9 eV emission peak is related to the intrinsic carrier recombination. They reported that Auger recombination process is significant in nanoparticles, and the increased final state density and reduced dielectric constant can be related to the enhancement of the Auger recombination. In our work we did not observe low energy PL emission bands however we observed low dielectric constants compare to high temperature grown STO films. This might be due to carrier recombination.

Moreover, PL emission peak intensity further increased after the post-deposition annealing. It is known that photoemission in STO thin films is due to the defect levels related to oxygen deficiency and doping. As reported by Kan et al.\(^{[10]}\), irradiation with \(Ar^+\) ions improves the PL emission of STO films as a direct function of the irradiation time. According to Kan et al., \(Ar^+\) ion treatment produces defect levels and the observed blue emission can be attributed to defects that are related with oxygen deficiency. In their study, they also studied the emission spectrum of oxygen deficient crystalline STO thin films deposited at 700 °C, and observed that the films show wide blue emission.

In general, it is accepted that post-deposition annealing leads to an overall reduction in defect-related luminescence and improves crystalline quality (as also revealed by XRD measurement, see Fig. 1). In the present study, red shift observed for the PL emission peak might be caused by the re-organization of defect levels and band gap shrinkage due to the renormalization effect\(^{[33]}\).

### 3.3. Electrical properties

Electrical properties of the as-deposited and annealed STO thin films were extracted from the \(C-V\) and \(I-V\) characteristics of Ag/STO/p-Si MIS capacitor structures. The \(C-V\) behavior of the STO\(^{\text{st}}\) thin film at different frequencies is illustrated in Fig. 7(a), as an example. The three typical regions of a \(C-V\) curve, which are the accumulation, depletion and inversion, were clearly observed for all of the four plots given in Fig. 7(a). Dielectric constants were calculated from these plots, using the maximum capacitance values in the accumulation region, as a function of different oxygen concentrations and post-deposition annealing. In Fig. 7(b), dielectric constants of as-deposited and annealed STO\(^{\text{st}}\) and STO\(^{\text{st}}\) films are presented as a function of frequency. Lower \(\varepsilon_{\text{STO}}\) values were obtained for films deposited at high oxygen flow rates. Furthermore, \(\varepsilon_{\text{STO}}\) Values of the film sputtered in pure \(Ar\) ambient were found to be more stable, compare to films deposited in oxygen rich environment, as a function of frequency. Dielectric constants (\(@100\) kHz) were in the range of 38–66 for as-deposited films, which decreased to ~30 after post-deposition annealing irrespective of the deposition conditions. This might be due to the interfacial states, which occur after annealing. Although greater dielectric constant values, in the range of 250–800, are reported for high temperature-grown STO thin films, the \(\varepsilon_{\text{STO}}\) Values obtained in the present work are in good agreement with those previously reported for films deposited at low temperatures\(^{[1, 45, 46]}\). Low dielectric constant values might be caused by small crystallite sizes and the accommodation of interface layers, which is known to lower the polarization in perovskite lattice\(^{[47]}\). Sakabe et al.\(^{[48]}\) studied the effects of grain size on dielectric properties of BaTiO\(_3\) ceramics, and reported that the dielectric constant increases with crystallite size. STO\(^{\text{st}}\) thin films, after post-deposition annealing process, exhibited \(C-V\) hysteresis behavior independent of the measurement frequency. Fig. 7(c) shows the dc voltage sweeping from positive to negative bias at 50 kHz, and the following reverse sweeping. Dawber et al.\(^{[49]}\)

<table>
<thead>
<tr>
<th>O(_2)/O(_2) + Ar</th>
<th>As-deposited</th>
<th>Annealed</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>(n)</td>
<td>(k)</td>
</tr>
<tr>
<td>0/0 + 30</td>
<td>2.06</td>
<td>0.04</td>
</tr>
<tr>
<td>3/3 + 27</td>
<td>2.09</td>
<td>0.00</td>
</tr>
<tr>
<td>6/6 + 24</td>
<td>2.05</td>
<td>0.00</td>
</tr>
</tbody>
</table>

Fig. 5. Spectral refractive index plots of as-deposited and annealed STO thin films.

Fig. 6. Photoluminescence spectra of as-deposited and annealed thin films deposited on Si substrates.
defined this kind of a butterfly loop, where the capacitance is different for increasing or decreasing voltages, as one of the important ferroelectric material characteristics. However, in the literature, the butterfly loop was mostly attributed to charge injection, and carrier trapping and/or space charge redistribution in the under electrode area, or net positive charges which cause a positive shift during the voltage sweep [49,50]. Furthermore, it might also be explained by the switching of ferroelectric domains [49]. Interesting enough to note, this phenomenon was not detected in the as-deposited films. To comprehensively understand this behavior, further investigations, such as \( P-E \) and pulsed \( C-V \) measurements are in progress.

\( I-V \) measurements were carried out in order to estimate the dielectric breakdown voltage (\( V_{bd} \)), dielectric breakdown field (\( E_{bd} \)) and CSC of the STO films. Typical \( I-V \) characteristics of the Ag/STO/p-Si MIS capacitor structure measured with dc voltage in the range of \(+10 \text { to } -10 \text { V}\) are depicted in Fig. 8. The calculated \( V_{bd} \) values were 3.4 and 4.8 V for as-deposited, and 3.3 and 5.8 V for annealed STO\( ^0 \) and STO\( ^{20} \) thin films, respectively. For films sputtered using 10% O\( _2 \), a lower \( V_{bd} \) value of 1.9 V was obtained; however, we did not observe any breakdown for the annealed STO\( ^{10} \) thin film up to 30 V. The \( E_{bd} \) and corresponding CSC values were calculated to be 0.14, 0.22, and 0.55 MV cm\(^{-1} \), and 0.75, 0.85, and 2.23 \( \mu \)C cm\(^{-2} \) for as-deposited STO\( ^0 \), STO\( ^{10} \), and STO\( ^{20} \) thin films, respectively. CSC of the annealed films was found to be 0.32 \( \mu \)C cm\(^{-2} \) for STO\( ^0 \), and 2.5 \( \mu \)C cm\(^{-2} \) for STO\( ^{20} \) thin films using the corresponding \( E_{bd} \) values. As can be seen from CSC values as-deposited and annealed STO thin films deposited at high oxygen flow (e.g., 20% \( O_2 \)) are promising particularly for DRAM applications.

4. Conclusion

STO thin film microstructure, surface morphology, optical, and electrical properties were studied as a function of oxygen concentration for as-deposited and post-deposition annealed films. Highly transparent and well-adhered films were deposited at RT. Amorphous behavior with some nano-crystallinity was observed for the as-sputtered thin films irrespective of the O\( _2 \) flow rate. Annealing at 700 °C for 1 h under O\( _2 \) ambient leads to crystallization of the STO layer deposited with a higher O\( _2 \) flow rate, which also significantly affected the optical and electrical characteristics of the resulting thin films. While as-sputtered STO films had very smooth surfaces, rms values of the annealed films, particularly the ones deposited using high oxygen concentration, were slightly higher than those of their as-deposited counterparts. Average optical transmissions of the as-deposited films improved in the VIS and NIR spectral regions with increasing O\( _2 \) flow rates. Moreover, annealing significantly enhanced the optical transmission by ~20% within the same spectrum. The optical band gap increased with O\( _2 \) flow rates, and its value remained unchanged for the films deposited in O\( _2 \)-rich environments. Refractive indices of STO films slightly increased with the post-deposition annealing treatment. Processing parameters such as deposition pressure, O\( _2 \) concentration, and deposition and annealing temperatures have significant influence on the structural, optical and electrical properties of sputtered STO thin films. Although dielectric constants of the annealed films decreased to ~30 due to interfacial states that occur after annealing, relatively high dielectric constants in the range of 30 to 66 at 100 kHz were obtained for <300 nm-thick STO films deposited at RT.


